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The semiconductor assembly as claimed in 26, wherein the encapsulant is compliant.

The semiconductor assembly as claimed in claim M, wherein said lead portions and said terminals are formed by photochemical etching or by electrodeposition techniques.

## **REMARKS**

The present preliminary amendment presents new claims 61-89, amends the title and the abstract to more accurately describe the scope of the presently claimed invention, and amends the specification to correct typographical errors and to reference prior copending nonprovisional applications under 37 C.F.R. 1.78 (a)(2). The present preliminary amendment should be entered because it is fully supported by the specification and introduces no new matter.

The new claims are supported by the disclosure of the present application, which in turn is identical to commonly assigned parent Patent Application No. 08/861,280 and earlier applications 08/319,966 and 08/030,194. For example, the specification at pages 49-64 describes "face-up" chip mountings, including those presently claimed. At page 64, lines 14-22 of the present application, the bonding wires are described. The 08/030,194 Application was a continuation of Application No. 07/765,928, now issued U.S. Patent No. 5,347,159. The claims presented by this amendment are related to the claims of the '159 patent in that the present claims are directed to semiconductor assemblies having the contacts of a chip on a front surface of the chip and a backing element facing the rear surface of the chip, the backing element having terminals

connected to the contacts through lead portions, where the terminals are movable with respect to the chip.

The new claims are believed presently allowable and do not introduce new matter. Accordingly, Applicant respectfully requests entry of this amendment and earnestly solicits allowance of all claims.

Respectfully submitted,

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